ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Pan-	C. Bannockł	burn, Illinois, A	ll rights reserved utions.	under both	This docum level parts, t	ent is a declarat	ion of the su	ibstances v s all lower	within the manufacture level materials for w	rer listed which the r	item. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and N	ials and Mfg Information				
Supplier Information														
Company name* Comp			ompany unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2023-06-08				
Contact Name	tact Name Title - Contact					Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Product Enviro Com			ro Compliance	Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representati			entative			Phone - Representative*			Email -	Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	ester Item Number Mfr Item N		Number Mfr Item Name			Effective Date	Pe Date Version Manufacturing Site			Weight*	UOM	Unit Type		
	NLV74H	LV74HC132ADR2G QUAD 2-INPUT NA		NAND SCHM	ITT	2023-06-08 PH1		H1	122.04		mg	Each		
Aanufacturing Proccess Informat	ion					·						· · ·		
Terminal Plating / Grid Array Mat	terial 7	ial Terminal Base Alloy J-		J-STD-020 MSI	L Rating	Peak Process Body Temperat		emperatur	ure Max Time at Peak Tempera		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	seco	nds 3				
omments														
vel 1 - maximum time at peak temperatu	re during so	ldering is 10-3	0 seconds											
or more information regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

select a RoHS exemption, if appli	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
sigma range of distribution unless Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg
			Supplier	Epoxy resins	129915-35-1		1.11	mg
Lead Frame	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg
Mold Compound-Black	43.43	mg		Epoxy resin	proprietary data		2.1715	mg
			Supplier	Phenolic Resin	Proprietary Data		2.1715	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.8686	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2172	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.0013	mg
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg
Wire Bond - Cu	0.3	mg	Supplier	Copper (Cu)	7440-50-8		0.3	mg